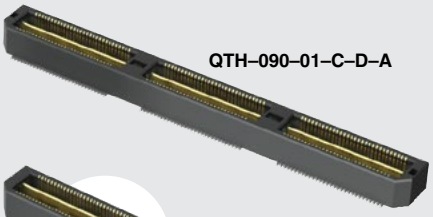
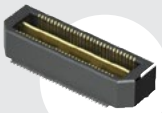
samtec

QSTRIP®

(0.50 mm) .0197"


QTH–060–07–F–D–A


QTH–090–01–C–D–A


QTH–030–01–L–D–A

QTH SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QTH

Insulator Material:
Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over 50 µ" (1.27 µm) Ni
Current Rating:
Contact:
2 A per pin
(2 pins powered)
Ground Plane:
25 A per ground plane
(1 ground plane powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
125 VAC (5 mm Stack Height)
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (030-060)
(0.15 mm) .006" max (090)*
*(.004" stencil solution may be available; contact IPG@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

PROTOCOLS

- 100 GbE
- Hypertransport™
- XAUI
- PCI Express®
- SATA
- InfiniBand™

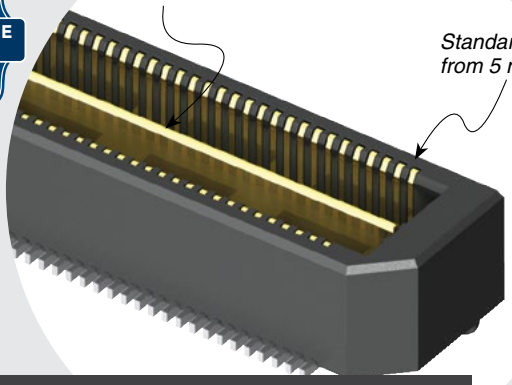
Note:
Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QSH
Cable Mates:
HQCD, HQDP
(See Also Available Note)
Standoffs:
SO

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

Integral metal plane for power or ground

Standard Stack Heights from 5 mm to 25 mm



ALSO AVAILABLE
(MOQ Required)

- 15 mm, 22 mm and 30 mm stack height
- 30 µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount & Guide Posts
- 80 (-DP), 120, 150 positions per row
- Retention Option

Contact Samtec.

HIGH-SPEED CHANNEL PERFORMANCE

QTH/QSH @ 5 mm Mated Stack Height
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

POWER/SIGNAL APPLICATION

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

QTH	–	PINS PER ROW NO. OF PAIRS	–	LEAD STYLE	–	PLATING OPTION	–	TYPE	–	A	–	OTHER OPTION

–030, –060, –090
(60 total pins per bank = –D)

–020, –040, –060
(20 pairs per bank = –D–DP)

Specify LEAD STYLE from chart

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

–L
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

***Note:** –C Plating passes 10 year MFG testing

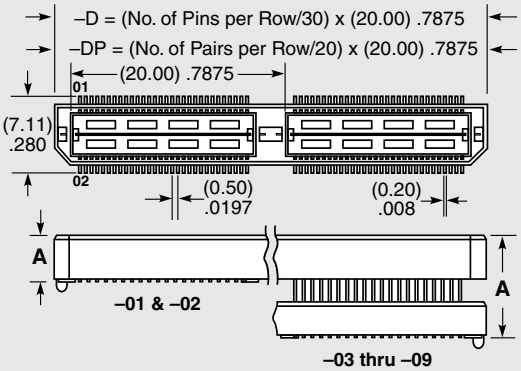
–D
= Single-Ended

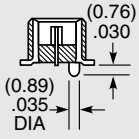
–D–DP
= Differential Pair (–01 only)

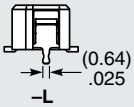
–K
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad (N/A with -05 & -07 lead style)

–TR
= Tape & Reel (–090 positions maximum)

–L
= Latching Option (–01 lead style only) (N/A on –060 (–D–DP) & –090)







QTH LEAD STYLE	A	HEIGHT WITH QSH*
–01	(4.27) .168	(5.00) .197
–02	(7.26) .286	(8.00) .315
–03	(10.27) .404	(11.00) .433
–04	(15.25) .600	(16.00) .630
–05	(18.26) .718	(19.00) .748
–07	(24.24) .954	(25.00) .984
–09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances